Final Product/Process Change Notification

Document # : FPCN21671X
Issue Date: 9 March 2017

Title of Change:	Change marking design and bonding method for WDFN6 devices
Proposed first ship date:	20 June 2017 or earlier after customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or < Mutsuki.Niki@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other _______________

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☒ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☒ Shipping/Packaging/Marking
☐ Other: _______________________

Sites Affected:

☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) :
ON Carmona, Philippines
ON Shenzhen, China
☐ External Foundry/Subcon site(s)

Description and Purpose:

This Process Change Notification is to notify customers of the following changes:

- Change marking design of WDFN6 to adopt the eject pin at mold release
- Change top mark from 3-liner to 2-liner
- Change WDFN device bonding method from bond stitch on lead to on ball (BSOB)

	Before Change					After Change				
	Description					Description				
Package design	No eject pin					Adopt the eject pin				
Part number	5111C01	5111C02	5111C05	5112C01	5132C01	5111C01	5111C02	5111C05	5112C01	5132C01
Marking design	05111 C01MT AYWW •	05111 C02MT AYWW •	05111 C05MT AYWW •	05112 C01MT AYWW •	05132 C01MT AYWW •	C0501 AYWW •	C0502 AYWW •	C0505 AYWW •	CB201 AYWW •	CD201 AYWW •
bonding method	Bond stitch on Lead (figure: Au wire, Die, Inner lead)					Bond stitch on Ball (figure: Au Bump; S2, VCC, GND, FET, IC, S1, CS, TST; ●: Change point)				

Reliability Data Summary:

QV DEVICE NAME: LC05132C01NMTTTG
PACKAGE: WDFN6

Test	Specification	Condition	Interval	Results
TC	JESD22-A104	Ta= -55°C to +125°C	500 cyc	0/231
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	-	-

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of affected Standard Parts:

Part Number	Qualification Vehicle
LC05111C01MTTTG	LC05132C01NMTTTG
LC05111C02MTTTG	
LC05111C05MTTTG	
LC05112C01MTTTG	
LC05132C01MTTTG	